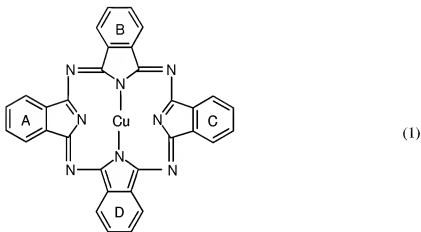


**AMENDMENTS TO THE CLAIMS:**

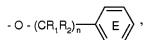
This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Currently Amended) A photosensitive resin composition comprising as a component (A) a halogen-free green colorant of the formula



in which the rings A, B, C and D are substituted by hydroxy or by the moiety



wherein R<sub>1</sub> is hydrogen or C<sub>1</sub>-C<sub>4</sub>-Alkyl, R<sub>2</sub> is hydrogen or C<sub>1</sub>-C<sub>4</sub>-Alkyl,

n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C<sub>1</sub>-C<sub>6</sub>alkyl, C<sub>1</sub>-C<sub>6</sub>alkoxy, hydroxy, NHCOR<sub>3</sub>, NH<sub>2</sub>SO<sub>2</sub>R<sub>4</sub> or SO<sub>2</sub>NHR<sub>5</sub>, wherein R<sub>3</sub> is C<sub>1</sub>-C<sub>4</sub>-Alkyl or phenyl, R<sub>4</sub> is C<sub>1</sub>-C<sub>4</sub>-Alkyl or phenyl and R<sub>5</sub> is [[is]] C<sub>1</sub>-C<sub>4</sub>-Alkyl or phenyl,

b) as a component (B) an alkali soluble reactive or unreactive oligomer or reactive or unreactive polymer-unreactive polymer,

c) as a component (C) a polymerizable monomer,

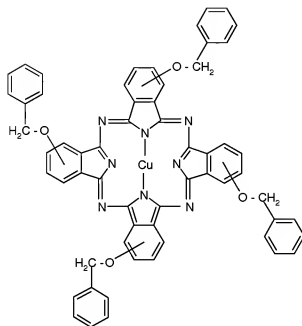
d) as a component (D) a photoinitiator,

e) as a component (E) an epoxy compound,

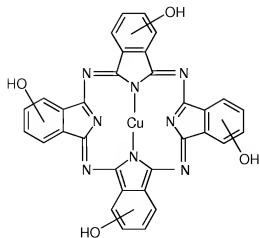
and also, if desired,

f) as a component (F) further additives.

2. (Original) A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



3. (Original) A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



4. (Withdrawn) Solder resist process, which process comprises the steps of

- (1) mixing the components (A) to (E) and if desired (F) according to claim 1,
- (2) applying the resulting composition to the substrate to generate a coated substrate,
- (3) evaporating the solvent, if present, at a temperature between 80-90°C,
- (4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,
- (5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,

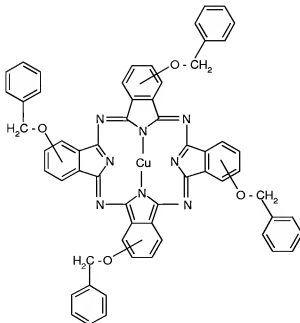
and

- (6) thermally curing the sample at a temperature about 150°C, thereby initiating the crosslinking between the carboxylic acid and the epoxy component.

5. (Withdrawn) Coated substrate obtained by the process according to claim 4.

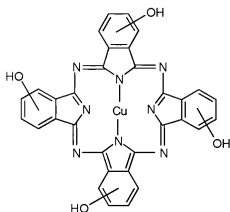
6. (Previously Presented) Substrate coated with the photosensitive resin composition according to claim 1.

7. (Withdrawn) Solder resist process according to claim 4, wherein component (A) of step (1) is the colorant of formula



(2).

8. (Withdrawn) Solder resist process according to claim 4, wherein component (A) of step (1) ) is the colorant of formula



(3).

9. (Withdrawn) Coated substrate obtained by the process according to claim 7.

10. (Withdrawn) Coated substrate obtained by the process according to claim 8.

11. (Previously Presented) Substrate coated with the photosensitive resin composition according to claim 2.

12. (Previously Presented) Substrate coated with the photosensitive resin composition according to claim 3.

13. (Previously Presented) A photosensitive resin according to claim 1, wherein the polymerizable monomer is a vinyl monomer.